Suwon, South Korea – October 28 & 29, 2024

TestConX한국 Korea

English version follows

2024 년 10 월 28~29 일에 개최되는 첫번째 TestConX® Korea 행사에 여러분을 초대합니다.

이틀일정으로 진행되는 TestConX Korea 는 최신기술 및 업계동향에 대한 인사이트를 제공하는 세션파트와 국내 외 유력 테스트 업체들의 솔루션을 직접 확인할 수 있는 TestConX EXPO 행사로 구성되어 있습니다.

테스트 공정 전문가들과 클라이언트가 한 자리에 만나는 TestConX Korea 는
서로의 인사이트를 공유하고 비즈니스 기회를 모색할 수 있는 최적의 장소로
참석하는 분들 모두에게 좋은 기회가 될 것입니다.

아울러 TestConX Korea 에서는
Ultra-high volume operation 및 Millimeter-wave 기술을 포함한
5G Testing 과 관련해 인사이트를 나눠 주실 연사를 찾고 있습니다.
추가적으로 테스트와 Burn-in 에 대한 발표 제안도 큰 의미가 있을 것 같습니다.

Presentation 시간은 30 분으로 (발표 25 분, Q&A 5 분)
TestConX 에서 제공하는 PPT 양식을 사용하여 영어 또는 한국어로 발표할 수 있고,
발표를 위한 제안서는 250~300 단어로 작성해 하단 주소로 보내주시면 됩니다.

□ 세부 일정
제안서 제출 : 7 월 12 일 (금)
결과 통보 : 8 월 2 일 (금)
자료 제출 : 9 월 30 일 (금)

□ 양식 / 제출처
https://testconx.org/korea-abstracts
korea-abstracts@testconx.org

다음 주제 목록을 참조해 주세요

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Join us for the 2nd annual TestConX® Korea workshop to be held as a **live in-person event** on October 28 & 29, 2024. We will have tutorials on Monday October 28. Followed by a full day of technical presentations and the TestConX EXPO where you will find the latest in test products and solutions on Tuesday October 29. *Don't miss the preeminent Korean event focused on connecting electronic test professionals to solutions.*

The TestConX Korea Technical Program Committee is especially seeking presentations that highlight the challenges and solutions for High Bandwidth Memory, including singulated die and known good stack, -testing along with Chiplet package testing. Other proposals on a broad range of test and burn-in topics, as illustrated below, are also highly valued.

Each presentation at TestConX Korea is provided a thirty-minute presentation slot (approximately 25 minutes for the presentation with 5 minutes for questions and answers). Authors may choose to present in English or Korean. And authors only need to prepare a PowerPoint presentation. (There is no paper to write.)

Please submit a 250-to-500-word abstract for presentations of your original, previously unpublished, technical presentation by July 12, 2024.

Submit via:

- Online form https://testconx.org/korea-abstracts

or

- Email korea-abstracts@testconx.org including title of presentation, complete contact information (name, affiliation/company name, job title, email address, phone number, and mailing address) for each author, and name of presenter.

Abstracts will be reviewed and authors will be notified around August 2, 2024.

Presentation submissions are due September 30, 2024.

Language: Presentation in English or Korean. PowerPoint slides in English using the TestConX provided template with the option to also create Korean slides.

발표 주제에 대해서 제한은 없습니다. 아래 Test 관련된 분야를 참고하시면 됩니다.
Topics that address the **challenges of these and other test applications** include, but are not limited to:

Test applications of highest interest include:

- High Bandwidth Memory testing - including singulated die and known good stack testing
- System Level Test – especially for LPDDR memory and Chiplet packaging
- Smartphone & 5G/6G including antenna in package (AiP) and mm-wave
- Electric vehicles - power, sensing, and battery test

Electrical & Mechanical Challenges in package testing

- High frequency and high data rate techniques and technologies including 5G and mm-wave
- Wafer Level Packages (WLP) and Panel Level Processing (PLP)
- High current, high power, and/or high temperature device testing
- Handler & change kit designs and considerations
- Fine Pitch Kelvin Contacting
- Thermal management and modelling
- Contact technology
- Bare Die, system on a chip (SOC), system-in-package (SiP), and 2/2.5/3D package testing
- Wafer level chip scale (WLCSP) test for Known Good Die (KGD) or final test

Test Process & Operational Challenges

- Over the Air (OtA) and Antenna in Package (AiP) testing
- System Level Test (SLT)
- Test & Burn-in floor operations
- Socket repair, cleaning, and re-plating methods
- Massively parallel and non-singulated test (Wafer Level and Panel Level)
- Test strategies for reducing qualification and production time
- Socket & PCB verification, checkout, & qualification
- Strip Testing and Test-in-Tray
- High reliability testing for mission critical and medical applications
- Microelectromechanical system (MEMS) and non-electrical (optical, fluidic, magnetic, acoustic, etc.) stimuli testing
- Bring-up, characterization, and validation
- Cloud and big-data analytics
- Design for testability including ATE test, SLT, and reliability test
- Failure analysis

Module & Product Test Challenges

- Fixturing and test contact
- Test automation
- Automated material handling
- Wireless testing at scale / high volume
- Thermal control

Printed Circuit Board (PCB) Design & Manufacturing Challenges

- For high temperature Burn-in board applications
- High data rate test applications
- Space Transformers and Ultra-fine pitch
- Board to Board Interconnects